WHAT IS CLAIMED IS:

1. A glass substrate machining method comprising the steps of:

machining a glass substrate by using a laser;

controlling an amount of air bubbles in said glass substrate to improve the workability of said glass substrate.

2. A glass substrate machining method comprising the steps of:

machining a glass substrate by using a laser;

controlling an amount of air bubbles in said glass substrate to improve the workability of said glass substrate, and wherein

a thin insulator is formed on a glass surface.

3. The glass substrate machining method according to claim 2, wherein said thin insulator on said glass surface is glass formed by coating.

4. The glass substrate machining method according to claim 2, wherein said thin insulator formed on said glass surface is an organic insulator film.

5. The glass substrate machining method according to claim 4, wherein said thin organic insulator on said glass surface is formed by coating.

6. The glass substrate machining method according to claim 4, wherein said thin insulator on said glass surface

is made into a sheet form by using a laminator.

7. A glass substrate machining method comprising the steps of:

machining a glass substrate by using a laser;

controlling an amount of air bubbles in said glass substrate to form a vacancy only inside of said glass substrate.

8. A glass substrate machining method comprising the steps of:

machining a glass substrate by using a laser;

controlling an amount of air bubbles in a glass substrate so that said glass substrate, after said laser machining, has a large surface area on the machined surface due to bubble traces in glass; and

forming a metal film through simple electroless plating, to improve heat radiation property of the metal-film-formed portion.

9. The glass substrate machining method according to claim 1, wherein a CO_2 laser is used to perform the laser machining.

10. The glass substrate machining method according to claim 2, wherein a CO_2 laser is used to perform the laser machining.

11. The glass substrate machining method according to claim 7, wherein a CO_2 laser is used to perform the laser

machining.

12. The glass substrate machining method according to claim 8, wherein a CO_2 laser is used to perform the laser machining.

13. A glass substrate machining method comprising the steps of:

machining a glass substrate by using a CO_2 laser of variable pulse width as machining means;

a first step of executing a single laser irradiation; and

a second step of executing a plurality of laser irradiations.

14. The glass substrate machining method according to claim 13, wherein the pulse width of said laser in the second step is greater than that in the first step.

15. A high-frequency circuit fabricating method using the glass substrate machining method according to claim 1, wherein a CO_2 laser is used to perform the laser machining.

16. A high-frequency circuit fabricating method using the glass substrate machining method according to claim 2, wherein a CO_2 laser is used to perform the laser machining.

17. A high-frequency circuit fabricating method using the glass substrate machining method according to claim 7, wherein a CO_2 laser is used to perform the laser machining.

18. A high-frequency circuit fabricating method using

the glass substrate machining method according to claim 8, wherein a CO_2 laser is used to perform the laser machining.

19. A radio terminal apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 1, wherein a CO_2 laser is used to perform the laser machining.

20. A radio terminal apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 2, wherein a CO_2 laser is used to perform the laser machining.

21. A radio terminal apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 7, wherein a CO_2 laser is used to perform the laser machining.

22. A radio terminal apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 8, wherein a CO_2 laser is used to perform the laser machining.

23. A radio base station apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 1, wherein a CO_2 laser is used to perform the laser machining.

24. A radio base station apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 2, wherein a CO_2 laser

is used to perform the laser machining.

25. A radio base station apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 7, wherein a CO_2 laser is used to perform the laser machining.

26. A radio base station apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 8, wherein a CO_2 laser is used to perform the laser machining.

27. A radar apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 1, wherein a CO_2 laser is used to perform the laser machining.

28. A radar apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 2, wherein a CO_2 laser is used to perform the laser machining.

29. A radar apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 7, wherein a CO_2 laser is used to perform the laser machining.

30. A radar apparatus comprising a high-frequency circuit fabricated by using the glass substrate machining method according to claim 8, wherein a CO_2 laser is used to perform the laser machining.